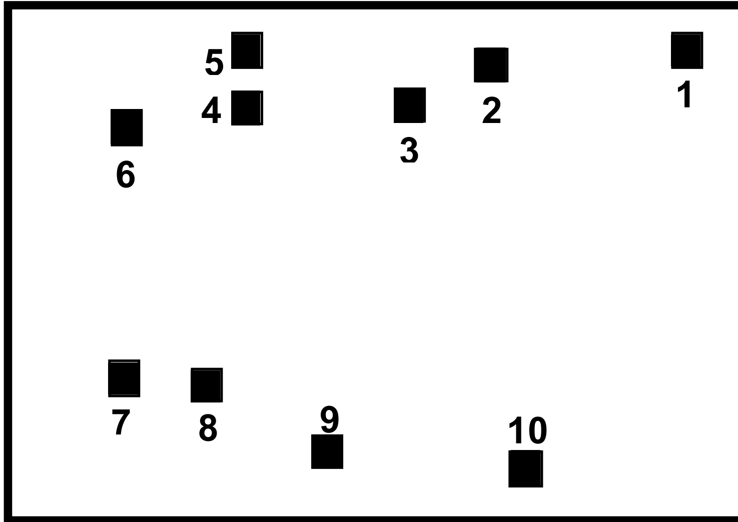
Supertex inc.

HV826-6in
Die Specifications



Pad Coordinates in Microns

Pad #	Function	X (µm)	Y (µm)
1	V_{DD}	0.0	0.0
2	Rsw-osc	-601.0	-39.5
3	REL-osc	-856.5	-152.5
4	DGND	-1341.5	-153.5
5	AGND	-1339.5	8.5
6	SWGND	-1705.5	-209.5
7	Lx	-1723.5	-936.5
8	Cs	-1476.5	-956.5
9	V_B	-1173.0	-1163.5
10	V_A	-567.0	-1222.0

Die Specifications

	mils	mm		
Die Size:	90.16 x 59.45	2.290 x 1.510	**Back Side Metal:**	None
Die Thickness:	8.0 ±1.0	0.203 ±0.025	**Back Side Potential:**	Gnd
Bond Pad Size:	4 x 4	0.103 x 0.103	**Die Attach Material:**	Epoxy Ablestick 84-1 or Equal
Bond Wire Size:	1.3	0.033	**Bond Pad Metal:**	Al/Si/Cu

8/7/03

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